## RECEIVED

MAY 2 3 2005

**RESPONSE UNDER 37 CFR 1.116 EXPEDITED PROCEDURE EXAMINING GROUP 2818** 

> PATENT APPLICATION Docket No.: 8750-045

Client Ref. No.: SPX200306-0020US

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: In-Ku KANG

Serial No.:

10/632,700

Examiner:

Tran, Mai Huong C.

Filed:

July 31, 2003

Group Art Unit:

2818

Confirmation No.:

3617

For:

MULTI-CHIP MODULE HAVING BONDING WIRES AND

METHOD OF FABRICATING THE SAME

Mail Stop AF Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

## AMENDMENT AFTER FINAL REJECTION UNDER 37 CFR 1.116

Responsive to the Final Office Action, Paper No. 102005, dated March 22, 2005, please amend the application as follows.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 6 of this paper.